T-51-10-08

MP7684A

CMOS

8-Bit High Speed Analog-to-Digital Converter



FEATURES

- . Sampling Rates from 0.001 to 20 MHz (MSPS)
- 1/4 LSB DNL from 0.001 to 10 MHz
- 1/2 LSB DNL to 14 MHz
- Interface to any Input Range between GND and V_{DD}
- Pin Compatible Upgrade of MP7684
- Monotonic: No Missing Codes
- Single Power Supply (4 to 6 volt)
- CDIP, PDIP, SOIC & LCC Packages Available

- Low Power CMOS (300 mW)
- ESD Protection: 4000 Volts Minimum
- Latch-Up Free

BENEFITS

- Low Power for Lower System Noise
- . Most Flexible Input Range of any A/D Available
- No Sample/Hold Needed

GENERAL DESCRIPTION

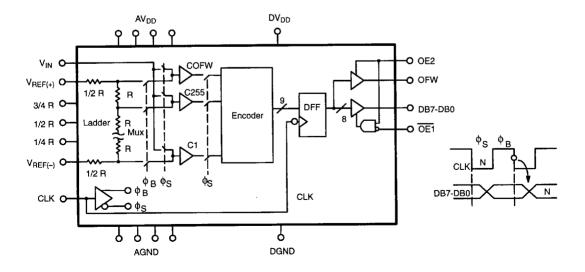
The MP7684A is an 8-bit monolithic CMOS single step high speed A/D converter designed for precision applications in video and data acquisition requiring conversion rates to 14 MHz with differential linearity error less than 1/2 LSB and low power consumption. A unique feature of this converter is its input architecture which eliminates the need for an input track and hold and allows full scale input ranges from 1.2 to 5 volts peak-to-peak, referred to ground or offset. The user simply sets V_{REF(-)} and V_{REF(+)} to encompass the desired input range.

The MP7684A includes 256 clocked comparators, encoders,

3-state output buffers, a reference resistor ladder and associated timing circuitry. An overflow bit (or flag) has been provided to make it possible to achieve 9-bit resolution by connecting two devices in parallel. In normal operation this flag has no effect on the data bits.

Specified for operation over the commercial / industrial (-40 to +85°C) and military (-55 to +125°C) temperature ranges, the MP7684A is available in Plastic (PDIP) and Ceramic (CDIP) dual-in-line, Surface Mount (SOIC), and Leadless Chip Carrier (LCC) packages.

SIMPLIFIED BLOCK AND TIMING DIAGRAM

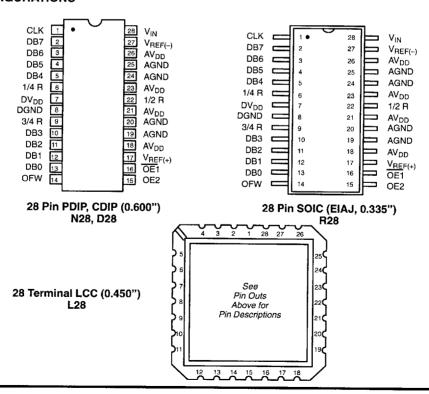




ORDERING INFORMATION

Package Type	Temperature Range	Part No.	DNL (LSB)	INL (LSB)	
Plastic Dip	−40 to +85°C	MP7684AJN	±1	±2	
Plastic Dip	-40 to +85°C	MP7684AKN	±3/4	±1 1/2	
SOIC	-40 to +85°C	MP7684AJS	±1	±2	
SOIC	-40 to +85°C	MP7684AKS	±3/4	±1 1/2	
LCC	-55 to +125°C	MP7684ASL	±1	±2	
LCC	–55 to +125°C	MP7684ASL/883	土1	±2	
LCC	-55 to +125°C	MP7684ATL	±3/4	±1 3/4	
LCC	-55 to +125°C	MP7684ATL/883	±3/4	±1 3/4	
Ceramic Dip	-40 to +85°C	MP7684AJD	±1	±2	
Ceramic Dip	-40 to +85°C	MP7684AKD	±3/4	±1 1/2	
Ceramic Dip	-55 to +125°C	MP7684ASD	±1	±2	
Ceramic Dip	-55 to +125°C	MP7684ASD/883	±1	±2	
Ceramic Dip	–55 to +125°C	MP7684ATD	±3/4	±1 3/4	
Ceramic Dip	–55 to +125°C	MP7684ATD/883	±3/4	±1 3/4	

PIN CONFIGURATIONS



PIN OUT DEFINITIONS

PIN NO.	NAME	DESCRIPTION			
1	CLK	Clock Input Pin			
2	DB7	Output Data Bit 7 (MSB)			
3	DB6	Output Data Bit 6			
4	DB5	Output Data Bit 5			
5	DB4	Output Data Bit 4			
6	1/4R	1/4 Point of Resistance Ladder			
7	DV _{DD}	Power Supply of Digital Circuit			
8	DGND	Digital Ground			
9	3/4R	3/4 Point of Resistance Ladder			
10	DB3	Output Data Bit 3			
11	DB2	Output Data Bit 2			
12	DB1	Output Data Bit 1			
13	DB0	Output Data Bit 0 (LSB)			
14	OFW	Digital Output Overflow			
15	OE2	Output Enable Control 2			
16	OE1	Output Enable Control 1			
17	V _{REF(+)}	Positive Reference Voltage Pin			
18	AV _{DD}	Power Supply of Analog Circuit			
19	AGND	Analog Circuit Ground			
20	AGND	Analog Circuit Ground			
21	AV _{DD}	Power Supply of Analog Circuit			
22	1/2R	Center of Resistance Ladder			
23	AV _{DD}	Power Supply of Analog Circuit			
24	AGND	Analog Ground			
25	AGND	Analog Ground			
26	AV _{DD}	Power Supply of Analog Circuit			
27	V _{REF(-)}	Negative Reference Voltage Pin			
28	VIN	Analog Input			



ELECTRICAL CHARACTERISTICS TABLE

Unless Otherwise Specified: $AV_{DD} = DV_{DD} = 5 \text{ V}$, $F_S = 14 \text{ MHz}$ (50% Duty Cycle),

 $V_{REF(+)} = 4.1 \text{ V}, V_{REF(-)} = AGND, T_A = 25^{\circ}C$

D			25°0			to Tmax		
Parameter	Symbol	Min	Тур	Max	Min	Max	Units	Test Conditions/Comments
STATIC PERFORMANCE (1)								
Resolution (All Grades) Sampling Rate	N	8			8		Bits	
	F _S	0.001		14	0.001	14	MHz	For Specified Accuracy
ACCURACY (J Grade)	ĺ				l		Ì	
Differential Non-Linearity	DNL			±3/4		±1	LSB	
Integral Non-Linearity	INL			±1 1/2		±2	LSB	Best Fit Line (Max INL – Min INL)/2
Zero Scale Error Full Scale Error	EZS EFS		30				mV	(MAX MAC - MINI MAC)/2
	EFS		15				m∨	
ACCURACY (K Grade)								
Differential Non-Linearity Integral Non-Linearity	DNL		1/3	±1/2		±3/4	LSB	
Zero Scale Error	INL EZS		4/5 30	土1	}	±1 1/2	LSB mV	Best Fit Line
Full Scale Error	EFS		15				mV	
ACCURACY (S Grade)	[
Differential Non-Linearity	DNL			±3/4		±1	LSB	
Integral Non-Linearity Zero Scale Error	INL EZS			±1 1/2		±2	LSB	Best Fit Line
Full Scale Error	EFS		30 15				mV mV	
ACCURACY (T Grade)								
Differential Non-Linearity	DNL		1/3	±1/2		±3/4	LSB	
Integral Non-Linearity	INL		4/5	土1		土13/4	LSB	Best Fit Line
Zero Scale Error Full Scale Error	EZS EFS		30 15				mV mV	
REFERENCE VOLTAGES								
Positive Ref. Voltage	V _{REF(+)}			AVDD		,, [.,	
Negative Ref. Voltage	V _{REF(-)}	AGND		AVDD	AGND	AV _{DD}	V V	
Differential Ref. Voltage (3) Ladder Resistance	V _{REF}	1.0 170	ΑV _I 225	300	1.0 AV	V _{DD} -AGND 330	V Ω	
Res. Temp. Coefficient (2)	R _{TCO}	170	225	300	130	330	12	
(Tmin to Tmax)						3000	ppm/°C	
ANALOG INPUT						1		
Input Voltage Range (12)	V _{IN} V	REF(-)	_ v	REF(+)	/ _{REF(-)}	V _{REF(+)}	V p-p	
Input Capacitance (4) Aperture Delay (2)	C _{IN}		50 15			ĺ	pF ns	
Aperture Uncertainty (Jitter) (2)	t _{AJ}		45				ps	



ELECTRICAL CHARACTERISTICS TABLE (CONT'D)

Description	Symbol	Min	25°C Typ	Max	Tmin to Min	Tmax Max	Units	Conditions
Logical "1" Voltage Logical "0" Voltage Leakage Currents (5) CLK OE2 (6) OE1 (7) Input Capacitance	ViH ViH	2.0 -10 -50 -5	5	0.8 10 5 50	2.0 -10 -50 -5	0.8 10 5 50	V V μΑ μΑ μΑ pF	V _{IN} =DGND to DV _{DD}
Clock Timing (See Figure 9.) Clock Period (2) Rise & Fall Time (8) "High" Time (Auto-balance) "Low" Time (Sampling)	ts t _R , t _F t _B ts	50 35 35	50	5	50	5 500,000	ns ns ns ns	No max limit
Logical "1" Voltage Logical "0" Voltage Tristate Leakage Data Hold Time (2) Data Valid Delay (2) Data Enable Delay (2) Data Tristate Delay (2)	VOH VOL IOZ tHLD tOL tOEN tDHZ	DV _{DD} -0.5 -10 13	17 25	0.4 10 33 20 20	DV _{DD} -0.8 -15 11	5 0.4 15 35 25 25	V V μA ns ns ns	(See Fig. 1 & 2) C _{OUT} =50 pF I _{LOAD} = 4 mA I _{LOAD} = 4 mA V _{OUT} =DGND to DV _{DD}
POWER SUPPLIES Operating Voltage (AV _{DD} , DV _{DD}) Current (AV _{DD} + DV _{DD})	V _{DD}	4	50	6 80	4	6 85	V mA	(9)
AC PARAMETERS (2) Signal Noise Ratio (10) Differential Gain Error Differential Phase Error	SNR SNR d _G		46 45 2 1				dB dB % Degree	RMS/RMS Meas. F _S = 3X NTSC F _S = 4X NTSC F _S = 3X NTSC



ELECTRICAL CHARACTERISTICS TABLE (CONT'D)

NOTES

- Tester measures code transitions by dithering the voltage of the analog input (ViN). The difference between the measured and the ideal code width (V_{REF}/256) is the DNL error (Figure 3.). The INL error is the maximum distance (in LSB's) from the best fit line to any transition voltage (Figure 4.). Accuracy is a function of the sampling rate (Fs).
- (2) Guaranteed; Not tested.
- Specified values guarantee functionality. Refer to other parameters for accuracy. (3)
- See V_{IN} input equivalent circuit (Figure 5.). Switched capacitor analog input requires driver with low output resistance. (4)
- (5)All inputs have diodes to DVDD and DGND. Input OE1 has internal pull down. Input OE2 has internal pull up. Input DC currents will not
- exceed specified limits for any input voltage between DGND and DVDD. (6)
- Internal resistor to DV_{DD} biases unconnected input to active high logical level. Internal resistor to DGND biases unconnected input to active low logical level. (7)
- Condition to meet aperture delay specifications (t_{AP}, t_{AJ}). Actual rise/fall time can be less stringent with no loss of accuracy. (8)
- DV_{DD} and AV_{DD} are connected through the silicon substrate. DC voltages differences will cause undesirable internal currents. (9)
- (10)SNR: Ratio of fundamental over noise.

Specifications are subject to change without notice

ABSOLUTE MAXIMUM RATINGS (1, 2, 3) (TA = +25°C unless otherwise noted)

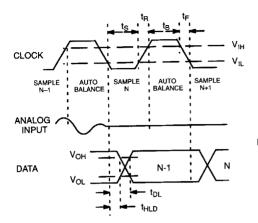
V_{DD} to GND+7 V $V_{REF(+)}$ & $V_{REF(-)}$ GND -0.5 to V_{DD} +0.5 V V_{IN} GND -0.5 to V_{DD} +0.5 V	Storage Temperature
All Inputs	CDIP, PDIP, SOIC, LCC

NOTES:

- Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation at or above this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.
- Any input pin which can see a value outside the absolute maximum ratings should be protected by Schottky diode clamps (HP5082-2835) from input pin to the supplies. All inputs have protection diodes which will protect the device from short transients outside the supplies of less than 100mA for less than 100 μ s. V_{DD} refers to AV_{DD} and DV_{DD} . GND refers to AGND and DGND.

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OE1 OE2 t_{DEN} **tDEN** DATA DB7-DB0 DATA DATA DATA DATA **OFW**

Figure 1. MP7684 Timing Diagram

Figure 2. Output Enable/Disable Timing Diagram

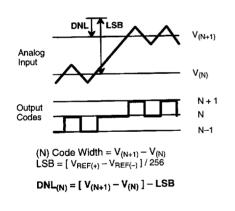


Figure 3. DNL Measurement

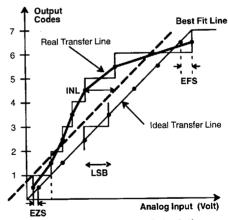


Figure 4. INL Error Calculation

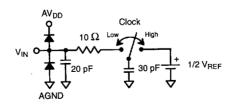


Figure 5. Analog Input Equivalent Circuit

THEORY OF OPERATION

Analog-to-Digital Conversion

The MP7684A converts analog voltages into 256 digital codes by encoding the outputs of 255 comparators. A 256th comparator is used to generate the overflow bit. The conversion is synchronous with the clock and is accomplished in 1.5 clock periods. Data is transferred from the comparator latches to the output registers each clock period at the same time the input is sampled.

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The clock signal generates the two internal phases, ϕB (CLK high = balance) and ϕS (CLK low = sample). ϕB connects the comparators to the reference tap points. ϕS connects the comparators to the analog input voltage.

The reference resistance ladder is a series of 257 resistors. The first and the last resistor of the ladder are half the value of the others so that the following relations apply:

$$R_{REF} = 256 * R$$
 $V_{REF} = V_{REF(+)} - V_{REF(-)} = 256 * LSB$

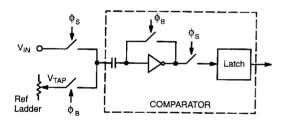


Figure 6. MP7684A Comparator

The MP7684A comparators use the balance phase (ϕ_B) to charge one plate of the capacitors to the reference ladder tap point (V_{TAP}) and the other to the inverter/comparator trigger point. During the sample phase (ϕ_S) one plate of the capacitors switches to V_{IN} . The change in voltage $(V_{IN}-V_{TAP})$ transfers across the capacitor and forces the inverter into one of the two possible logic states. A latch (connected to the comparator during ϕ_S) restores and propogates the digital level to the encode logic.

The rising edge of the CLK input marks the end of the sampling phase (ϕ_S). Internal delay of the clock circuitry will delay the actual instant when ϕ_S disconnects the latch from the comparator. This delay is called aperture delay (t_{AP}).

The aperture delay is not constant but it changes from one cycle to the next. Internal thermal noise, power supply noise and slow input clock edges are major contributors to this variation. The aperture jitter $(t_{A,J})$ is the variation of the aperture delay distribution.

This uncertainty shows as digital code errors if the input slew rate multiplied by $t_{A,J}$ is of the same order of magnitude as the

LSB. That is, if $(dv/dt) * t_{AJ} \approx V_{REF}/256$ an internal logic error of one LSB of error results.

Accuracy of Conversion: DNL and INL

The transfer function for an ideal A/D converter is shown in Figure 7.

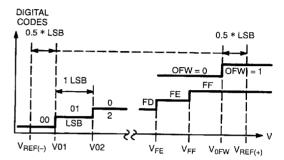


Figure 7. Ideal A/D Transfer Function

The overflow transition (V_{0FW}) takes place at:

$$V_{IN} = V_{OFW} = V_{REF(+)} - 0.5 * LSB$$

The first and the last transitions for the data bits take place at:

$$V_{REF} = (V_{REF(+)} - V_{REF(-)})$$

$$V_{IN} = V01 = V_{REF(-)} + 0.5 * LSB$$

$$V_{IN} = V_{FF} = V_{REF(+)} - 1.5 * LSB$$

LSB =
$$V_{REF} / 256 = (V_{FF} - V01) / 254$$

Note that the overflow transition is a flag and has no impact on the data bits.

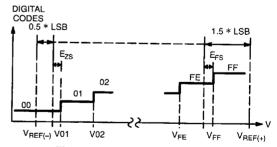


Figure 8. Real A/D Transfer Curve

In a "real" converter the code-to-code transitions do not fall exactly every $V_{REF}/256$ volts.

A positive DNL (Differential Non Linearity) error means that the real width of a particular code is larger than 1 LSB. This error is measured in fractions of LSB's.

A Max DNL specification guarantees that ALL code widths (DNL errors) are between the stated value. A specification of

Max DNL = ± 0.5 LSB means that all codes are within 0.5 and 1.5 LSB. If $V_{REF} = 4.096 \text{ V}$ then 1 LSB = 16mV and every code width is between 8 and 24 mV.

The formulas for Differential Non-linearity (DNL), Integral Non-Linearity (INL) and zero and full scale errors (EZS, EFS)

DNL
$$(01) = V02 - V01 - LSB$$

:::

DNL (FE) = V_{FF} - V_{FE} - LSB

EFS (full scale error) = $V_{REF(+)} - 1.5 * LSB - V_{FF}$

EZS (zero scale error) = V_{REF(-)} + 0.5 * LSB - V01

Figure 4. shows the zero scale and full scale error terms.

Systems that adjust the V_{REF} voltages to correct for EFS and EZS only increase the accuracy at the two extreme points. In the MP7684A, such adjustments have little impact at frequencies lower than 10 MHz. Refer to the characterization data for temperature and frequency dependence.

Figure 4. gives a visual definition of the INL error. The chart shows a 3 bit converter transfer curve with greatly exaggerated DNL errors to show the deviation of the real transfer curve from the ideal one.

After a tester has measured all the transition voltages, a line is drawn parallel to the ideal transfer line. By definition the Best Fit Line makes equal the positive and and the negative INL errors. This may change an INL of -1 to +2 LSB's relative to the Ideal Line into a ±1.5 relative to the Best Fit Line.

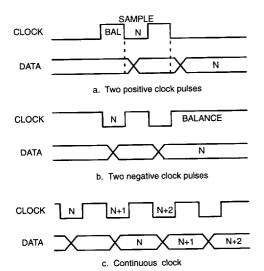


Figure 9. Relationship of Data to Clock

Clock Timing

A system will clock the MP7684A continuously or it will give clock pulses intermittently when a conversion is desired. The timing of Figure 9. keeps the MP7684A comparators in balance and ready to sample the analog input. This mode draws the most current from V_{DD}. The timing of Figure 9. leaves the comparator inputs floating (and AC coupled to the VIN input) and a balance phase is needed before a valid sampling phase. In this mode, IDD varies because of the floating comparator inputs.

Analog Input

The MP7684A has very flexible input range characteristics. The user sets $V_{REF(+)}$ and $V_{REF(-)}$ to two fixed voltages and then varies the input DC and AC levels to match the V_{REF} range.

A more common use of this flexibility is to first design the analog circuitry and then to adjust the reference voltages to match the analog input range. It is good design practice to proceed with these steps:

- estimate V_{RFF} range
- design analog circuitry
- prototype analog circuitry and debug with ADC clocked 3)
- 4) adjust V_{REF} range

Good driving capabilities (low resistance, high current) of circuitry driving the flash analog input are guaranteed to optimize the MP7684A performance. These have an impact above 5 MHz and they are very important above 10 MHz. Use of Current Feedback Amplifiers is an easy and cost effective way to maximize performance.

Reference Voltages

If the input bandwidth is limited to the Nyquist region (F_{IN} < Fs/2) then the two reference voltages can be set at any two values between the supplies. VREF (their difference) can be reduced down to 1.5 volts with minor change in accuracy. If the input bandwidth exceeds Fs/2 then it is recommended that VREF be lower than VDD/2.

At V_{REF} = 1.5 V the LSB is reduced to 6mV. Further reductions show an increased error in terms of LSB (which is getting smaller) even if the error in terms of mV remains constant.

The input/output relationship as a function of V_{RFF}:

$$A_{IN} = V_{IN} - V_{REF(-)}$$
DATA = 256 * (A_{IN}/V_{REF})

- a) Gain adjustment. A system can increase total gain by reducing V_{RFF}
- b) Increasing Dynamic Range. A system can increase dynamic range by using DACs to control VREF and by "focusing" on input ranges of interest. In digitizing "static" information (an image in a scanner) the first digitization would point to the input range in which most of the output codes fall. The system then would adjust the DACs to generate

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V_{REF(+)} and V_{REF(-)} to include just the range of interest for the second and final pass.

c) Subranging; Increasing resolution. Where practical. multiple passes at different V_{RFF} ranges can increase resolution without changing hardware. A system needs to make four passes to increase the resolution to 10 bits. The merging of the data from the four passes can create DNL errors at the borders of the ranges. One solution is to "overlap" the ranges and to use software methods to properly merge the ranges.

Digital Interfaces

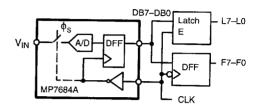
The logic encodes the 255 bits into a binary code and latches the data in a D-type flip-flop for output. The inputs OE1 and OE2 control the output buffers in an asynchronous mode.

OE1	OE2 OFW		DB7-DB0	
х	0	High Z	High Z	
1	1	Valid	High Z	
0	1	Valid	Valid	

Table 1. Output Enable Logic

If another DFF follows the ADC, it is recommended that the system latches the data at the negative going edge of the clock. This will work at any frequency. If the system must latch with the positive going edge then care must be taken to avoid the overlay of the clock edge with the changing outputs.

If a latch follows the ADC, the positive half of the clock used as enable signal guarantees stable output at the end of the enable pulse.



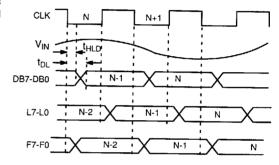
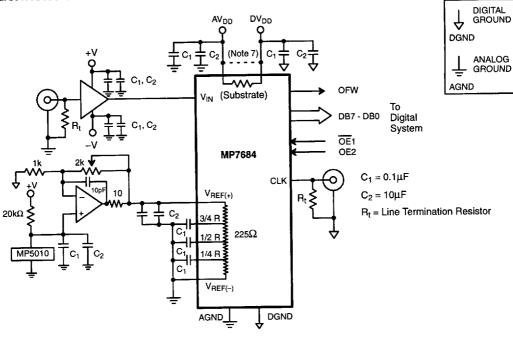


Figure 10. MP7684A Functional Equivalent Circuit and Interface Timing



APPLICATION NOTES



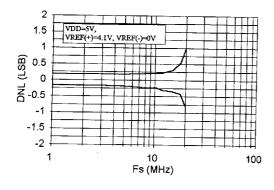
Typical Circuit Connections

- 1. All signals should not exceed AV $_{DD}$ +0.5 V or AGND -0.5 V or DV_{DD} +0.5 V or DGND -0.5 V.
- 2. Any input pin which can see a value outside the absolute maximum ratings (AVDD or DVDD+0.5 V or AGND -0.5 V) should be protected by diode clamps (HP5082-2835) from input pin to the supplies. All MP7684A inputs have input protection diodes which will protect the device from short transients outside the supply ranges.
- 3. The design of a PC board will affect the accuracy of MP7684A. Use of wire wrap is not recommended.
- 4. The analog input signal (V_{IN}) is quite sensitive and should be properly routed and terminated. It should be shielded from the clock and digital outputs to minimize cross coupling and noise pickup.
- 5. The analog input should be driven by a buffer op amp with as low output impedance as possible. The impedance should be less than 50Ω for clock frequencies above 10 MHz.

- 6. Analog and digital ground planes should be substantial and common at one point only. The ground plane should act as a shield for parasitics and not a return path for signals. To reduce noise levels, use separate low impedance ground paths.
- DV_{DD} should not be shared with other digital circuitry. DV_{DD} should be connected to AVDD next to the MP7684A.
- 8. DV_{DD} and AV_{DD} are connected inside the MP7684A through the N - doped silicon substrate. DC voltage differences between DV_{DD} and AV_{DD} will cause undesirable in-
- 9. The power supplies and reference voltages should be decoupled with a ceramic (0.1 μ F) and a tantalum (10 μ F) capacitor as close to the device as possible.
- 10. The digital output should not drive long wires. The capacitative coupling and reflection will contribute noise to the conversion. When driving distant loads, buffers should be used.



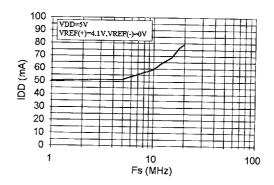
PERFORMANCE CHARACTERISTICS



4 3 VDD=5V, VREF(+)=4.1V, VREF(-)=0V 2 PD=5V, PD=

Graph 1. DNL vs. Sampling Frequency

Graph 2. INL vs. Sampling Frequency



Graph 3. I_{DD} vs. Sampling Frequency